Apparatus for mounting components on a substrate

ABSTRACT

An apparatus for the mounting of components (1) on a substrate (3) comprises a pick and place system (5) with a bonding head (6), a camera (7) and two optical deflection systems (8, 9). The first optical deflection system (8) and the camera (7) form a first image detection system for recording an image of the substrate location (2) on which the component is to be mounted. The first optical deflection system (8), the second optical deflection system (9) and the camera (7) form a second image detection system for recording an image of a bottom side of the component (1). The pick and place system (5) moves the carriage (13) from a take-up location of the component (1) to the substrate location (2) in a respective predetermined height H_1 above the second optical deflection system (9), so that the bottom side of the component (1) is located in a focal plane of the camera (7), and lifts the carriage (13) to a respective predetermined height H_2, so that the substrate location (2) is situated in the focal plane of the camera (7).

(Fig. 1)